

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3268436

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JONG MIN JANG	12/23/2014
HEE SUB LEE	12/23/2014
WON YOUNG ROH	12/23/2014
JONG HYEON CHAE	12/23/2014
JOON SUP LEE	12/23/2014
DAEWOONG SUH	12/23/2014
HYUN A KIM	12/23/2014
SEON MIN BAE	12/23/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEOUL VIOSYS CO., LTD.
<b>Street Address:</b>	65-16, SANDAN-RO 163 BEON-GIL
<b>Internal Address:</b>	DANWON-GU, GYEONGGI-DO
<b>City:</b>	ANSAN-SI
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14578199
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	114896-8027.US00
<b>NAME OF SUBMITTER:</b>	MICHELLE MELENDEZ
<b>SIGNATURE:</b>	/Michelle Melendez/

PATENT

<b>DATE SIGNED:</b>	03/17/2015
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**Total Attachments: 5**

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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Jong Min Jang et al.

Application No.: Not Yet Assigned

Conf. No.: Not Yet Assigned

Filed: Herewith

For: TEMPLATE FOR GROWING SEMICONDUCTOR,  
METHOD OF SEPARATING GROWTH SUBSTRATE  
AND METHOD OF FABRICATING LIGHT EMITTING  
DEVICE USING THE SAME

**DECLARATION AND ASSIGNMENT BY THE INVENTOR  
UNDER RULE 37 C.F.R. § 1.63 EFFECTIVE ON SEPTEMBER 16, 2012**

As a below named inventor, I hereby declare that:

I believe I am the sole original inventor or an original joint inventor of a claimed invention in a patent application entitled:

**TEMPLATE FOR GROWING SEMICONDUCTOR, METHOD OF  
SEPARATING GROWTH SUBSTRATE AND METHOD OF FABRICATING LIGHT  
EMITTING DEVICE USING THE SAME**

filed on December 19, 2014, and assigned U.S. Application Number 14/578,199, the specification of which is attached hereto and identified as Attorney Docket No. 114896-8027.US00. I authorize and request an attorney appointed in the above-identified U.S. application to hereafter insert above the filing date and application number of the above-identified U.S. patent application when known.

I believe the following persons are original joint inventors of the above-identified U.S. patent application:

Jong Min Jang;

Hee Sub Lee;

Won Young Roh;

Jong Hyeon Chae;

Joon Sup Lee;

Daewoong Suh;

Inventors : Jong Min Jang et al.  
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Hyun A. Kim; and

Seon Min Bae.

I made, authorized to make, or will make or authorize to make the above-identified patent application at the U.S. Patent and Trademark Office.

I have reviewed and understand the contents of the above-identified patent application including the claims.

I am aware of the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR §1.56.

I hereby acknowledge that any willful false statement made in the above declaration is punishable under 18 USC §1001 by fine or imprisonment of not more than five (5) years, or both.

#### ASSIGNMENT

I hereby assign to Seoul Viosys Co., Ltd., a corporation, having a place of business at 65-16, Sandan-ro 163 beon-gil, Danwon-gu, Ansan-si, Gyeonggi-do, Republic of Korea, and its successors and assigns (collectively "the Assignee"), the entire right, title and interest throughout the world in any and all inventions and improvements which are described in the above-identified application, and a prior Korean Patent Application No. 10-2013-0159325 filed in the Republic of Korea on December 19, 2013 from which the above-identified U.S. patent application claims priority and benefits.

This assignment includes the entire right, title and interest in the above-identified U.S. and Republic of Korea patent applications, all legal equivalents thereof in any country, any and all United States, Patent Cooperation Treaty, Republic of Korea and other foreign patents, utility models, and design registrations granted for any of said inventions and improvements, including, but not limited to, all divisions, continuations, reissues, reexamination certificates, any and all certificates issued in any post-grant proceeding, and extensions of said applications and patents of the United States, Patent Cooperation Treaty and Republic of Korea, all other foreign patents, utility models, and design registrations, and the right to claim priority based on the filing dates of the above-identified U.S. and Republic of Korea patent applications under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the

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European Patent Convention, and all other treaties of like purposes, and the right to seek relief and recover all damages, including, but not limited to, a reasonable royalty, by reason of infringement or any other violation of patent or patent application rights. I authorize the Assignee to apply in all countries in the name of the Assignee for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements.

In addition, I hereby confirm the sale, assignment, and transfer to the Assignee of the entire right, title and interest throughout the world in said inventions and improvements that occurred by operation of an employment agreement between me and the Assignee existing at the time said inventions and improvements were made. Should I have any remaining interest, I hereby sell, assign, and transfer any right, title and interest I may have in said inventions and improvements anywhere in the world to the Assignee.

The foregoing assignments, sale and transfer have been made for good and valuable consideration in accordance with the aforementioned employment agreement.

I hereby represent and covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into that would conflict with the assignment of said inventions and improvements to the Assignee.

I further covenant for myself and my respective heirs, legal representatives and assigns, to assist the Assignee in handling various procedures, tasks and documentation in connection with this assignment, including, but not limited to, providing to the Assignee promptly upon the request of the Assignee all pertinent facts and documents relating to said invention and improvements, and said patents, said legal equivalents or other legal instrument as may be known and accessible to me and testifying as to the same in any interference, litigation, or proceeding relating thereto, and promptly executing and delivering to the Assignee or its legal representative any and all papers, documents, instruments or affidavits in connection with obtaining, maintaining, issuing or enforcing said application, said inventions and improvements, and said patents, said equivalents and other legal instrument which may be necessary or desirable to carry out the purposes thereof.

I hereby authorize and request the Commissioner of Patents and Trademarks to issue one or more patents in the United States for said inventions and improvements to Seoul Viosys Co.,

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Ltd., as assignee of the entire interest, for the sole use and benefit of Assignee, its successors and assigns.

I am competent to execute the above declaration and assignment. I hereby have duly executed the declaration and assignment below with my name.

Full name of first inventor: Jong Min Jang

Inventor's signature: Jong Min Jang

Date: Dec. 23th, 2014

Full name of joint inventor: Hee Sub Lee

Inventor's signature: 이희섭

Date: Dec, 23th, 2014

Full name of joint inventor: Won Young Roh

Inventor's signature: 원영록

Date: Dec. 23th, 2014

Full name of joint inventor: Jong Hyeon Chae

Inventor's signature: 정현채

Date: Dec. 23th, 2014

Full name of joint inventor: Joon Sup Lee

Inventor's signature: 이준섭

Date: Dec 23th, 2014

Full name of joint inventor: Daewoong Suh

Inventor's signature: 다우웅수

Date: Dec. 23th, 2014

Full name of joint inventor: Hyun A. Kim

Inventor's signature: 김현아

Inventors : Jong Min Jang et al.  
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Filed : Herewith  
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Docket No.: 114896-8027.US00

Date: Dec. 23th. 2014

Full name of joint inventor: Seon Min Bae

Inventor's signature: 

Date: Dec. 23th. 2014.

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